

1. Part No. Expression

SLT161040G242P1A8

(a) (b) (c) (d) (e)

(a) Series Code

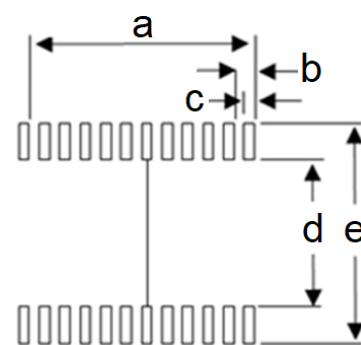
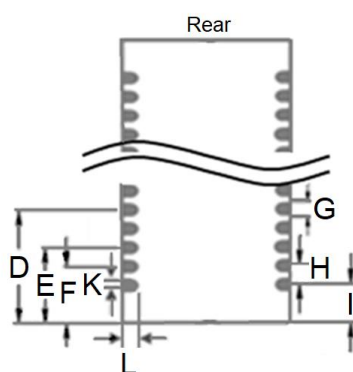
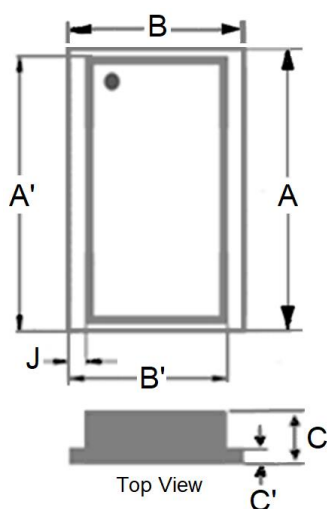
(d) Pin Code

(b) Dimension Code

(e) Control Code

(c) Material Code

2. Configuration & Dimensions (Unit: mm)

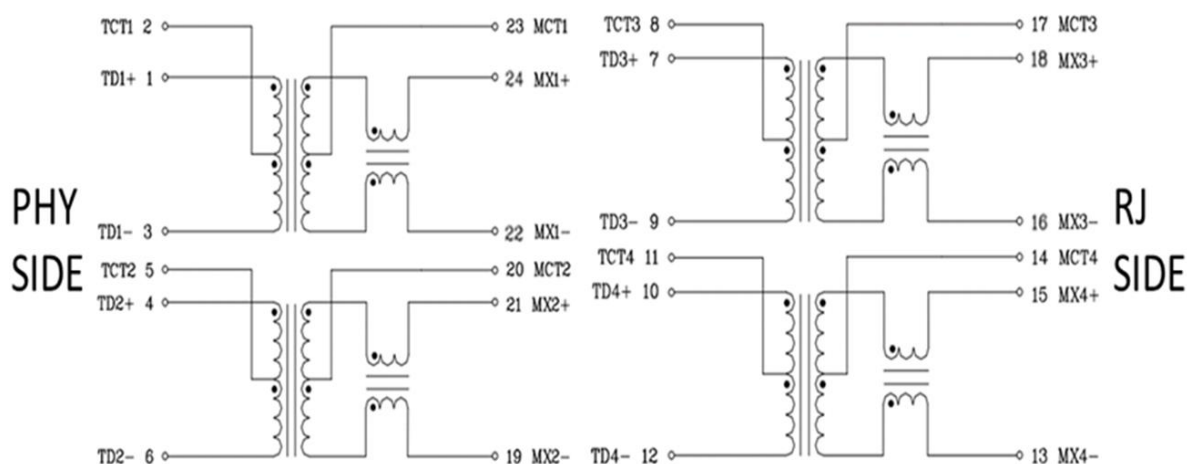


Recommended PCB Layout

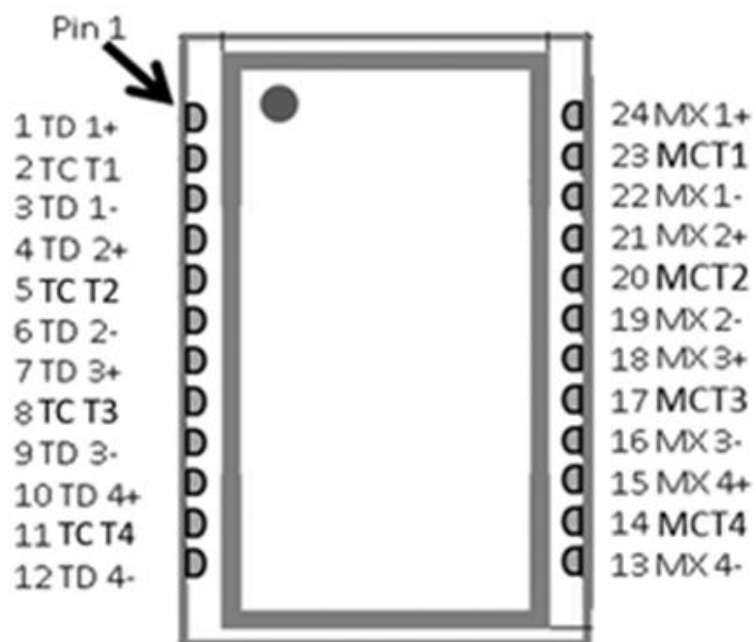
A	A'	B	B'	C
16.50±0.25	16.00±0.25	10.30±0.25	9.65±0.25	4.10±0.25
C'	D	E	F	G
0.80±0.05	6.75±0.25	4.75±0.25	3.75±0.25	0.40±0.05
H	I	J	K	L
1.00±0.25	2.75±0.25	0.65±0.05	0.20±0.05	1.00±0.25
a	b	C x 24	d	e
11.00±0.25	1.00±0.25	0.64±0.05	7.00±0.25	10.77±0.25

NOTE: Specifications subject to change without notice. Please check our website for latest information.

3. Schematic



4. Pin Define



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5. General Specifications

- (a) Operating Temp.: -40°C to +85°C (including self-temperature rise)
- (b) Storage Temp.: -40°C to +85°C (on board)
- (c) Humidity Range: 85±2% RH
- (d) Hi- Pot Resistance Test: 1500 VAC for 1 minute
- (e) Storage Condition (Component in its packaging)
 - i) Temperature: Less than 40°C
 - ii) Humidity: Less than 60% RH

6. Electrical Characteristics

Insertion Loss (dB) Max	Return Loss (dB) Min					Cross talk (dB) Min	DCMR (dB) Min	
1~100MHz	1~30MHz	40MHz	50MHz	60~80MHz	100MHz	1~100MHz	1~60MHz	60~100MHz
-1.1	-18	-14.4	-13.1	-12	-10	-35	-35	-30

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7. Soldering Specification

Mildly activated rosin fluxes are preferred. Our terminations are suitable for re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

7-1. IR Soldering Reflow

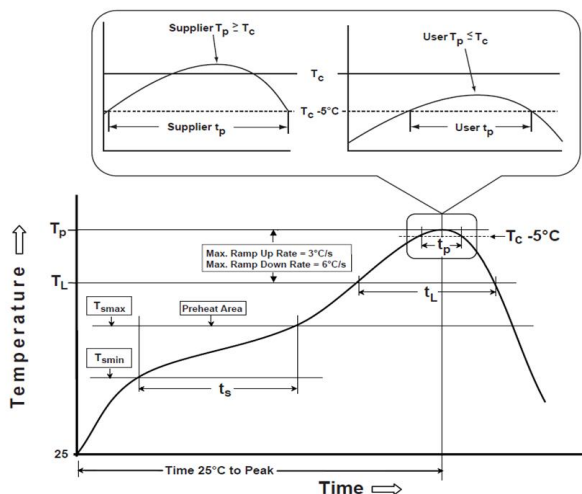
Recommended temperature profiles for lead free re-flow soldering in Figure 1, Table 1.1 & 1.2 (J-STD-020E).

7-2. Iron Reflow

Products attachment with a soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended (Figure 2).

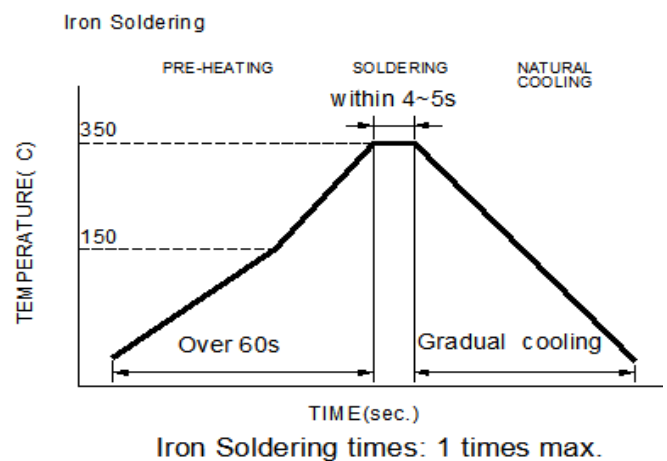
Note:

- Preheat circuit and products to 150°C.
- 355°C tip temperature (Max.)
- Never contact the ceramic with the iron tip
- 1.0mm tip diameter (Max.)
- Use a 20 watt soldering iron with tip diameter of 1.0mm
- Limit soldering time to 4~5 sec.



Reflow times: 3 times Max

Figure 1: IR Soldering Reflow



Iron Soldering times: 1 times max.

Soldering iron method: 350±5°C Max

Figure 2: Iron soldering temperature profiles

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Table (1.1) Reflow Profiles

Profile Type:	Pb-Free Assembly
Preheat	
-Temperature Min ($T_{\min}$)	150°C
-Temperature Max ($T_{\max}$)	200°C
-Time (t_s) from ($T_{\min}$ to $T_{\max}$)	60-120seconds
Ramp-up rate (T_L to T_p)	3°C /second max.
Liquids temperature (T_L)	217°C
Time (t_L) maintained above T_L	60-150 seconds
Classification temperature (T_c)	See Table (1.2)
Time (t_p) at $T_c - 5^\circ\text{C}$ (T_p should be equal to or less than T_c .)	* < 30 seconds
Ramp-down rate (T_p to T_L)	6°C /second max.
Time 25°C to peak temperature	8 minutes max.

T_p : maximum peak package body temperature, **T_c** : the classification temperature.

For user (customer) **T_p** should be equal to or less than **T_c** .

*Tolerance for peak profile temperature (T_p) is defined as a supplier minimum and a user maximum.

Table (1.2) Package Thickness/Volume and Classification Temperature (T_c)

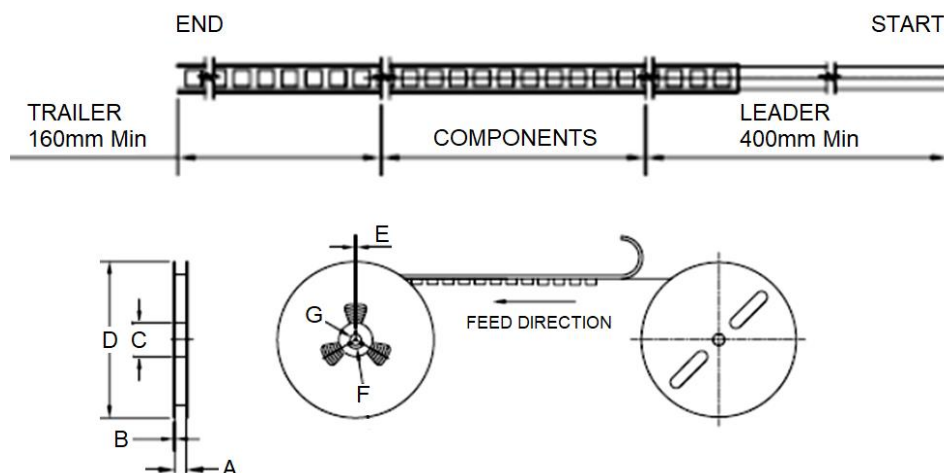
	Package Thickness	Volume mm ³ <350	Volume mm ³ 350-2000	Volume mm ³ >2000
PB-Free Assembly	<1.6mm	260°C	260°C	260°C
	1.6-2.5mm	260°C	250°C	245°C
	≥2.5mm	250°C	245°C	245°C

Reflow is referred to standard IPC/JEDEC J-STD-020E.

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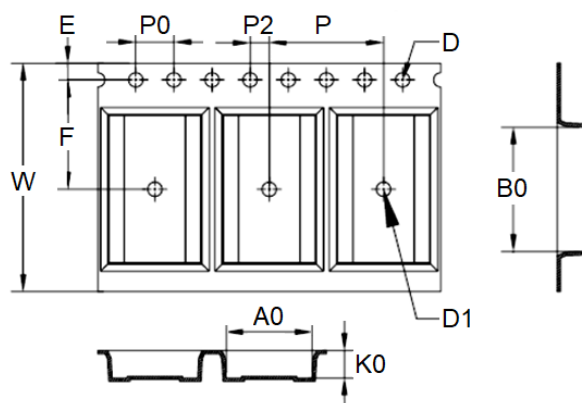
8. Packaging Information

8-1. Reel Dimension (Unit: mm)



Type	A	B	C	D	E	F	G
13"x32mm	33.5 Ref	2.0 Ref	100.0 Ref	330 Ref	2.5 Ref	Ø 21.5 Ref	Ø 13.0 Ref

8-2. Tape Dimension (Unit: mm)



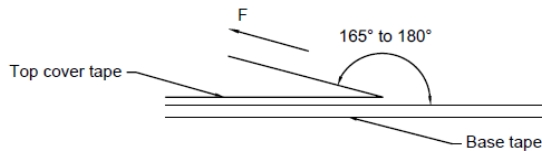
B0	A0	K0	P	P0	P2
16.80±0.10	10.60±0.10	4.90±0.10	16.00±0.10	4.00±0.10	2.00±0.10
W	F	D	D1	E	-
32.00±0.30	14.20±0.10	1.50±0.10	1.50 Min	1.75±0.10	-

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8-3. Packaging Quantity (Unit: Pcs)

Chip/ Reel	800
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8-4. Tearing Off Force



The force for tearing off cover tape is according to the follow table, in the arrow direction under the following conditions.

(Referenced ANSI/EIA-481-D-2008 of 4.11 standard)

Room Temp. (°C)	Room Humidity (%)	Room atm (hPa)	Tearing Speed (mm/min)
5~35	45~85	860~1060	300±10

Tape Size	8 mm	12 to 56 mm	72 mm or Wider
Tearing Off Force (grams)	10~100	10~130	10~150

Application Notice

1. Storage Conditions

To maintain the solderability of terminal electrodes:

- (a) Recommended products should be used within 12 months from the time of delivery.
- (b) The packaging material should be kept where no chlorine or sulfur exists in the air.

2. Transportation

- (a) Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- (b) Vacuum pick up is strongly recommended for individual components.
- (c) Bulk handling should ensure that abrasion and mechanical shock are minimized.

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